

**Hysol<sup>®</sup>****AC0305™**

January 2008

**PRODUCT DESCRIPTION**

AC0305™ provides the following product characteristics:

<b>Technology</b>	Solvent
<b>Components</b>	One part - requires no mixing
<b>Cure</b>	Room temperature cure
<b>Application</b>	Thinner

Under some conditions of use, Hysol<sup>®</sup> printed circuit coatings may require adjustment of viscosity and/or film thickness, this can be done by adding solvent. AC0305™ is a special blend of solvents designed to give moderately slow evaporation. Other solvents, such as Methyl Ethyl Ketone (MEK), Methoxy Propyl Acetate, Xylene, and Toluene, can be used alone or as a mixture depending on how coating will be applied and drying time desired. The evaporation rate of some recommended solvents starting with the fastest are as follows: Methyl Ethyl Ketone, Toluene, Xylene, Hysol<sup>®</sup> AC0305, Methoxy Propyl Acetate. Methyl Ethyl Ketone, Toluene, Xylene, Hysol<sup>®</sup> AC0305, Methoxy Propyl Acetate. Dilutions of 15-20% will generally be sufficient for most applications. Excess dilution may require additional applications to achieve the desired film build. When using solvents to dilute the coating, the board should be allowed to air dry at least 30 minutes at room temperature 25°C to remove solvent before oven cure or applying additional coats. the board should be allowed to air dry at least 30 minutes at room temperature. to remove solvent before oven cure or applying additional coats. If additional information is required, please contact your local technical representative.

**GENERAL INFORMATION**

**For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).**

**This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be used with chlorine or other strong oxidizing materials.**

**Not for product specifications**

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

**Storage**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: 8 °C to 21°C. Storage below 8 °C or greater than 28 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel

Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Conversions**

(°C x 1.8) + 32 = °F  
 kV/mm x 25.4 = V/mil  
 mm / 25.4 = inches  
 N x 0.225 = lb  
 N/mm x 5.71 = lb/in  
 N/mm<sup>2</sup> x 145 = psi  
 MPa x 145 = psi  
 N·m x 8.851 = lb·in  
 N·m x 0.738 = lb·ft  
 N·mm x 0.142 = oz·in  
 mPa·s = cP

**Note**

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

**Trademark usage**

Except as otherwise noted, all trademarks in this document are trademarks of Henkel Corporation in the U.S. and elsewhere. ® denotes a trademark registered in the U.S. Patent and Trademark Office.

Reference 0.1

Americas  
 +1.949.789.2500

Europe  
 +44.1442.278.000

Asia  
 +86.21.2891.8000

For the most direct access to local sales and technical support visit: [www.henkel.com/electronics](http://www.henkel.com/electronics)

